1. Record Nr. UNISA996394505703316

Titolo	The declaration of His Excellency the Lord General Fairfax, and his General Councel of officers, shewing the grounds of the Armies advance towards the City of London. By the appointment of His Excellency the Lord Fairfax, Lord General, and his General Councel of officers, held at Windsor, Nov. 30. 1648. Signed, John Rushvvorth, Secr' [[electronic resource]]
Pubbl/distr/stampa	London, : Printed by John Field for John Partridge, Novemb. 1. 1648
Descrizione fisica	8 p
Altri autori (Persone)	FairfaxThomas Fairfax, Baron, <1612-1671.>
Soggetti	Great Britain History Civil War, 1642-1649 Early works to 1800 Great Britain Politics and government 1642-1649 Early works to 1800 London (England) History 17th century Early works to 1800
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Annotation on Thomason copy: "Dec:"; 'Novemb.' in imprint has been crossed out. Reproduction of the original in the British Library.
Sommario/riassunto	eebo-0018

2. Record Nr. UNINA9910872627603321

Titolo	Adhesive Joining and Coating Technology in Electronics Manufacturing, 2000: 4th International Conference
Pubbl/distr/stampa	[Place of publication not identified], : I E E E, 2000
Descrizione fisica	1 online resource
Altri autori (Persone)	HyytiainenMarika
Disciplina	621.381/046
Soggetti	Protective coatings
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Bibliographic Level Mode of Issuance: Monograph
Sommario/riassunto	New isotropic conductive adhesive (ICA) for plated Sn or Sn/Pb electrode was developed. The new ICA and our existing ICA were evaluated for SMT as lead containing solder replacement, using on-chip resistors with plated Sn/Pb (90/10) and fired Ag/Pd terminations, from contact resistance and adhesion strength points of view. The new ICA gave more stable contact resistance and adhesion strength through reliability testing, even in the case of using 0/spl Omega/ chip resistor with plated Sn/Pb termination. Formation of boundaries or Sn grains on the surface and diffusion of Ni into Sn/Pb layer in the cross section, after chip resistors with plated Sn/Pb termination exposed to several reliability conditions, were observed by SEM and EDX. Though degree of these changes of plated Sn/Pb termination depends on each exposure condition, it can be estimated that the new ICA gets less influence by the changes of plated Sn/Pb termination and that it has some effect which prevents changing by plated Sn/Pb termination before it occurs.